MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

UQFN16 3x3, 0.5P
CASE 523BB
ISSUE O

DATE 31 OCT 2016

DOCUMENT NUMBER: 98AON13703G
DESCRIPTION: UQFN16 3x3, 0.5P

NOTES:
A. DESIGN CONFORMS TO JEDEC MO-248
B. ALL DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS AND TOLERANCES PER
   ASME Y14.5M, 2009
D. LAND PATTERN RECOMMENDATION FROM
   PCB MATRIX IPC LP CALCULATOR (V2009)

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